

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6844	align\$4 and (substrate wafer board) same (alignment adj3 (device equipment apparatus) stage) same (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:06
L2	14466	(substrate wafer board) same (alignment adj3 (device equipment apparatus) stage) same (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:07
L3	4389	(substrate wafer board) same (alignment adj3 (device equipment apparatus) stage) and (chip die ic) same (mark templates groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:09
L4	2245	(substrate wafer board) same (alignment adj3 (device equipment apparatus) stage) and (chip die ic) same (mark templates groove) and imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:42
L5	2014	l4 and (coordinat\$3 location point)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:40
L6	2117	(substrate wafer board) same (alignment adj3 (device equipment apparatus) stage) same (chip die ic) and (mark templates groove) and imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:27
L7	1931	l6 and (coordinat\$3 location point)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:28
L8	821	(substrate wafer board) same (alignment adj3 (device equipment apparatus) stage) and (chip die ic) same (mark templates groove) same imag\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/01/22 22:55